

<b>PATENT ASSIGNMENT COVER SHEET</b>
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SEOUL NATIONAL UNIVERSITY INDUSTRY FOUNDATION	11/24/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	CHEOL-SEONG HWANG
<b>Street Address:</b>	DOGOK REXLE APT. 410-402, DOGOK 2-DONG, GANGNAM-GU
<b>City:</b>	SEOUL
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Patent Number:</b>	7575940
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(312)427-6663
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>ATTORNEY DOCKET NUMBER:</b>	CU-5873 RJS-DS
<b>NAME OF SUBMITTER:</b>	RICHARD J. STREIT
<b>SIGNATURE:</b>	/RICHARD J. STREIT/
<b>DATE SIGNED:</b>	12/05/2016
<b>Total Attachments: 2</b>	
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source=cu5873_assignment_Hwang#page2.tif	

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UNITED STATES OF AMERICA  
ASSIGNMENT

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In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR:

SEOUL NATIONAL UNIVERSITY INDUSTRY FOUNDATION

hereby sells, assigns and transfers to

ASSIGNEE:

CHEOL-SEONG HWANG

(Dogok Rexle Apt. 410-402, Dogok 2-dong, Gangnam-gu, Seoul, Republic of Korea )

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the Application entitled DIELECTRIC FILM, METHOD OF MANUFACTURING THE SAME, AND SEMICONDUCTOR CAPACITOR HAVING THE DIELECTRIC FILM

and which is found in U.S. Patent No. 7,575,940 issued August 18, 2009 (U.S. Serial No. 11/830,227 filed July 30, 2007)

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, we have set our hand and seal

SEOUL NATIONAL UNIVERSITY  
INDUSTRY FOUNDATION

November 24, 2016

Date



Printed Name: CHOI YOUNG HO

Title: Senior Manager

*L&P 09/2012 (Assignment - entire interest - US rights only)*